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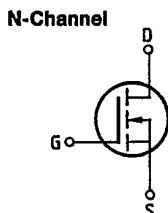
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T-39-11

BUZ 28

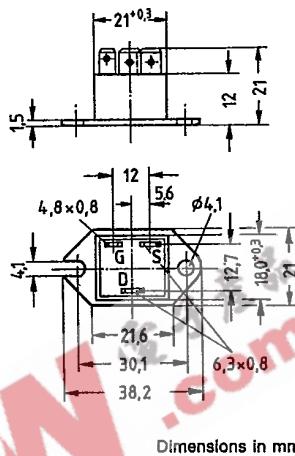
**SIEMENS AKTIENGESELLSCHAFT****Main ratings**

Drain-source voltage  $V_{DS}$  = 100 V  
 Continuous drain current  $I_D$  = 18 A  
 Drain-source on-resistance  $R_{DS(on)}$  = 0,1  $\Omega$



**Description** SIPMOS, N-channel, enhancement mode  
**Case** Plastic package TO 238 AA with insulated metal base plate in accordance with JEDEC, compatible with TO 3; AMP plug-in connections.  
 Approx. weight 21 g

Type	Ordering code
BUZ 28	C67078-A1608-A2



Dimensions in mm

**Maximum ratings**

Description	Symbols	Ratings	Units	Conditions
Drain-source voltage	$V_{DS}$	100	V	
Drain-gate voltage	$V_{DGA}$	100	V	$R_{GS} = 20 \text{ k}\Omega$
Continuous drain current	$I_D$	18	A	$T_C = 35^\circ\text{C}$
Pulsed drain current	$I_{Dpuls}$	70	A	$T_C = 25^\circ\text{C}$
Gate-source voltage	$V_{GS}$	$\pm 20$	V	
Max. power dissipation	$P_D$	70	W	$T_C = 25^\circ\text{C}$
Operating and storage temperature range	$T_J$	-40...+150	$^\circ\text{C}$	
Isolation test voltage	$V_{Is}$	3500	Vdc <sup>1)</sup>	$t = 1 \text{ min}$
DIN humidity category		F	-	DIN 40040
IEC climatic category		40/150/56	-	DIN IEC 68-1

**Thermal resistance**

Chip - case	$R_{thJC}$	$\leq 1,78$	K/W	
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<sup>1)</sup>) Isolation test voltage between drain and base plate referred to standard climate 23/50 in accordance with DIN 50014.

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**Electrical characteristics**(at  $T_j = 25^\circ\text{C}$  unless otherwise specified)

Description	Symbol	Characteristics			Unit	Conditions
		min.	typ.	max.		

**Static ratings**

Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	100	—	—	V	$V_{GS} = 0\text{V}$ $I_D = 0,25\text{mA}$
Gate threshold voltage	$V_{GS(\text{th})}$	2,1	3,0	4,0		$V_{DS} = V_{GS}$ $I_D = 1\text{mA}$
Zero gate voltage drain current	$I_{DSS}$	—	20 100	250 1000	$\mu\text{A}$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ $V_{DS} = 100\text{V}$ $V_{GS} = 0\text{V}$
Gate-source leakage current	$I_{GS}$	—	10	100	nA	$V_{GS} = 20\text{V}$ $V_{DS} = 0\text{V}$
Drain-source on-resistance	$R_{DS(\text{on})}$	—	0,09	0,1	$\Omega$	$V_{GS} = 10\text{V}$ $I_D = 9\text{A}$

**Dynamic ratings**

Forward transconductance	$G_{fs}$	4,0	8,0	—	S	$V_{DS} = 25\text{V}$ $I_D = 9\text{A}$
Input capacitance	$C_{iss}$	—	1500	2000		$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$
Output capacitance	$C_{oss}$	—	450	700	$f = 1\text{MHz}$	
Reverse transfer capacitance	$C_{rss}$	—	150	240		
Turn-on time $t_{on}$ ( $t_{on} = t_{d(on)} + t_r$ )	$t_{d(on)}$	—	30	45	ns	$V_{CC} = 30\text{V}$ $I_D = 3\text{A}$
	$t_r$	—	50	75		$V_{GS} = 10\text{V}$ $R_{GS} = 50\Omega$
Turn-off time $t_{off}$ ( $t_{off} = t_{d(off)} + t_f$ )	$t_{d(off)}$	—	170	220		
	$t_f$	—	80	110		

**Reverse diode**

Continuous reverse drain current	$I_{DR}$	—	—	18	A	$T_C = 25^\circ\text{C}$
Pulsed reverse drain current	$I_{DRM}$	—	—	70		
Diode forward on-voltage	$V_{SD}$	—	1,4	2,0	V	$I_F = 2 \times I_{DR}$ $V_{GS} = 0\text{V}, T_j = 25^\circ\text{C}$
Reverse recovery time	$t_{rr}$	—	200	—	ns	$T_j = 25^\circ\text{C}$
Reverse recovery charge	$Q_{rr}$	—	0,25	—	$\mu\text{C}$	$I_F = I_{DR}$ $dI_{F/dt} = 100\text{A}/\mu\text{s}$ $V_R = 30\text{V}$

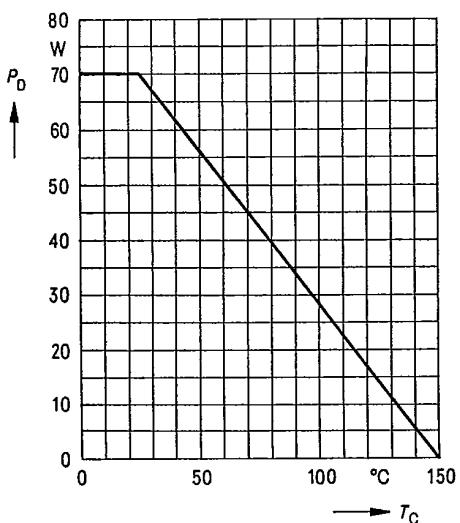
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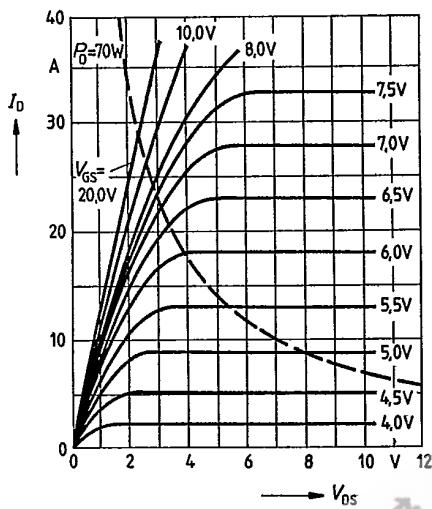
Power dissipation  $P_D = f(T_C)$



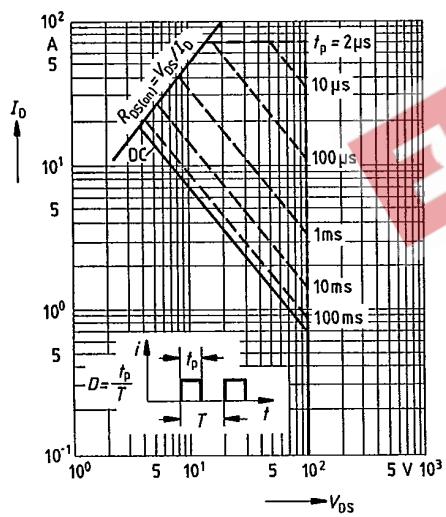
Typical output characteristics  $I_D = f(V_{DS})$

parameter: 80  $\mu$ s pulse test,

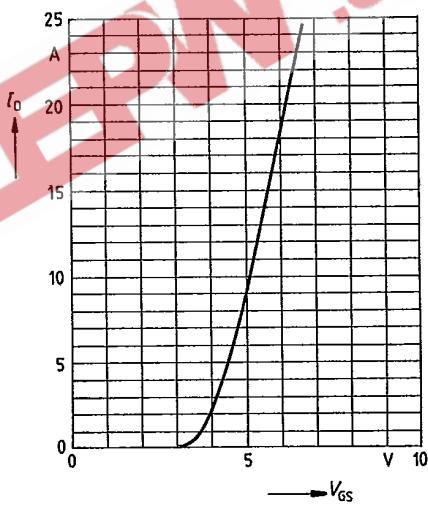
$T_J = 25^\circ\text{C}$



Safe operating area  $I_D = f(V_{DS})$   
parameter:  $D = 0.01$ ,  $T_C = 25^\circ\text{C}$



Typical transfer characteristic  $I_D = f(V_{GS})$   
parameter: 80  $\mu$ s pulse test,  
 $V_{DS} = 25V$ ,  $T_J = 25^\circ\text{C}$

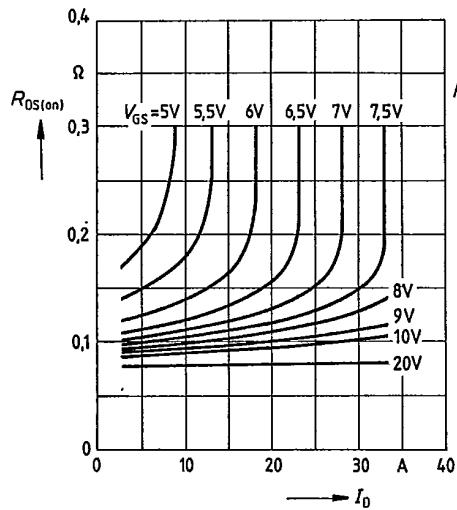


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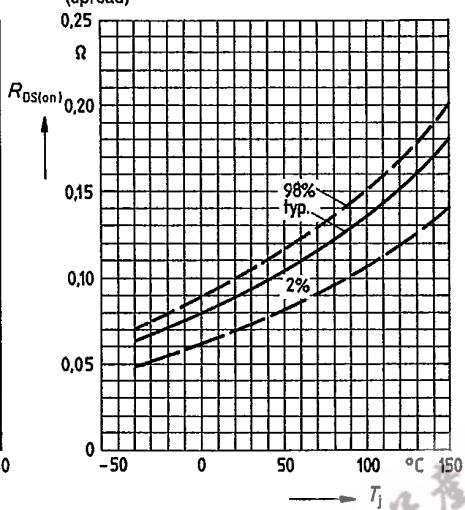
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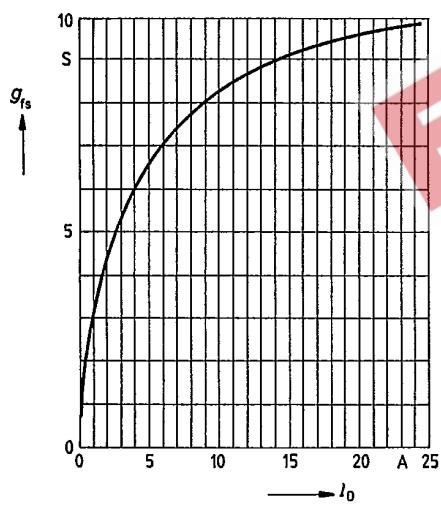
Typical drain-source on-state resistance  
 $R_{DS(on)} = f(I_D)$   
parameter:  $V_{GS}$ ,  $T_j = 25^\circ\text{C}$



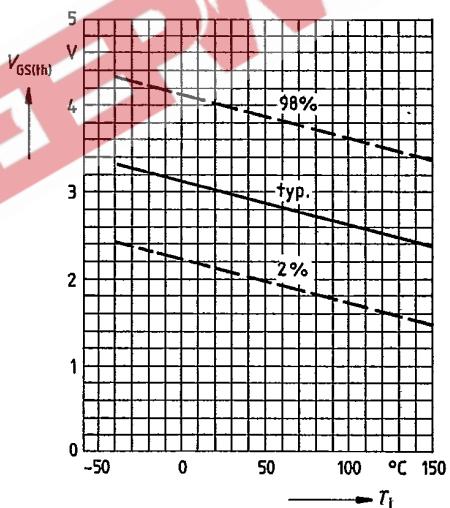
Drain-source on-state resistance  
 $R_{DS(on)} = f(T_j)$   
parameter:  $I_D = 9\text{A}$ ,  $V_{GS} = 10\text{V}$   
(spread)



Typical transconductance  $g_{fs} = f(I_D)$   
parameter: 80  $\mu\text{s}$  pulse test,  
 $V_{DS} = 25\text{V}$ ,  $T_j = 25^\circ\text{C}$



Gate threshold voltage  $V_{GS(th)} = f(T_j)$   
parameter:  $V_{DS} = V_{GS}$ ,  $I_D = 1\text{mA}$   
(spread)



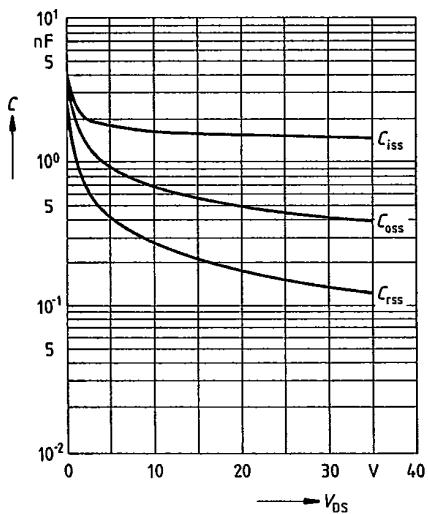
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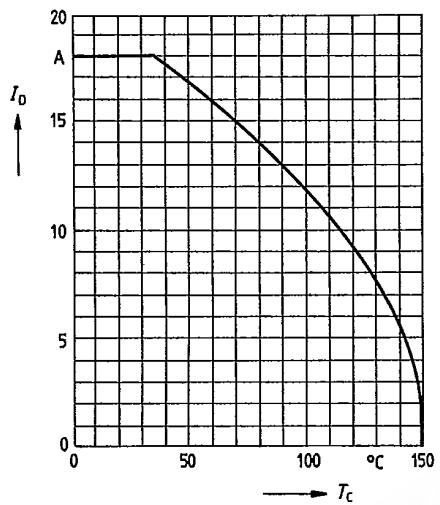
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Typical capacitances  $C = f(V_{DS})$   
parameter:  $V_{GS} = 0$ ,  $f = 1\text{MHz}$

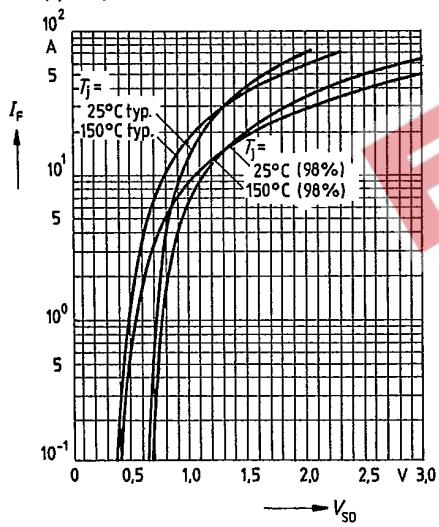


Continuous drain current  $I_D = f(T_C)$   
parameter:  $V_{GS} \geq 10\text{V}$



Forward characteristic of reverse diode

$I_F = f(V_{SD})$   
parameter:  $T_J$ ,  $t_p = 80 \mu\text{s}$   
(spread)



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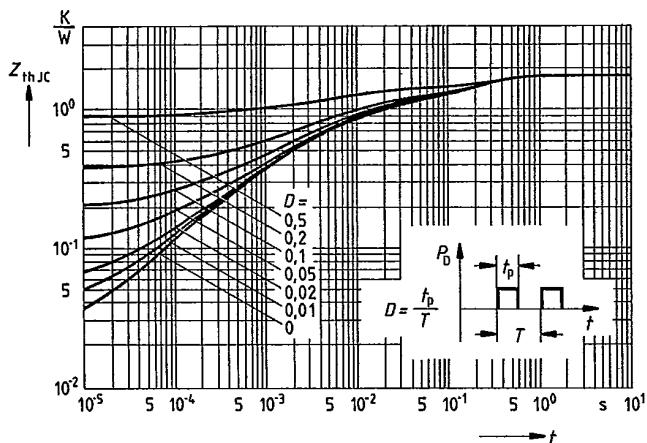
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Transient thermal impedance  $Z_{thJC} = f(t)$   
parameter:  $D = t_p/T$



Typical gate-charge  $V_{GS} = f(Q_{Gate})$   
parameter:  $I_D \text{ puls} = 28,5A$

